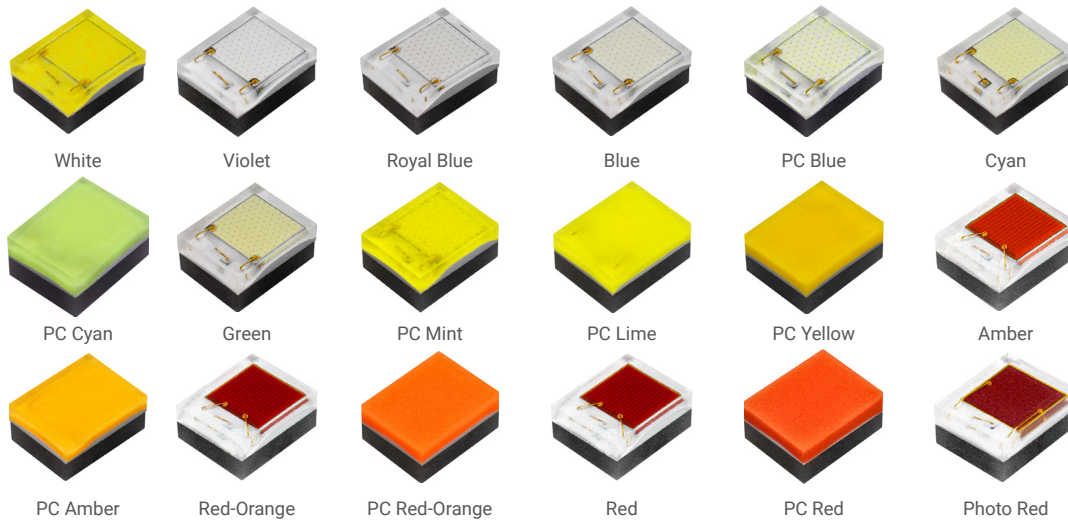


XLamp® Element G LEDs



INTRODUCTION

This application note applies to XLamp® Element G LEDs, called XE-G LEDs in this document, which have order codes in the following format.

XEGxxx-xx-xxxx-xxxxxxxxxx

This application note explains how XLamp XE-G LEDs and assemblies containing these LEDs should be handled during manufacturing. Please read the entire document to understand how to properly handle XLamp XE-G LEDs.

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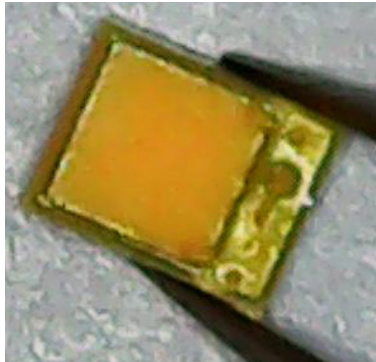
HANDLING XLAMP® XE-G LEDs

Manual Handling

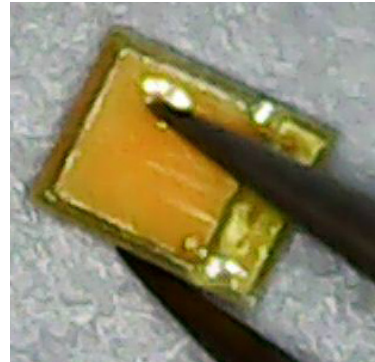
Use tweezers to grab XLamp XE-G LEDs at the base. Do not touch the lens with the tweezers. Do not touch the lens with fingers. Do not push on the lens.

Do not apply more than 600 g of shear force onto the lens. Excessive force on the lens could damage the LED.

✓
CORRECT



✗
WRONG



✓
CORRECT



✗
WRONG



Cree LED recommends the following at all times when handling XLamp XE-G LEDs or assemblies containing these LEDs:

- Avoid putting excessive mechanical stress on the LED lens.
- Never touch the optical surface with fingers or sharp objects. The LED lens surface could be soiled or damaged, which would affect the optical performance of the LED.
- Cree LED recommends always handling XE-G LEDs with appropriate ESD grounding.
- Cree LED recommends handling XE-G LEDs wearing clean, lint-free gloves.

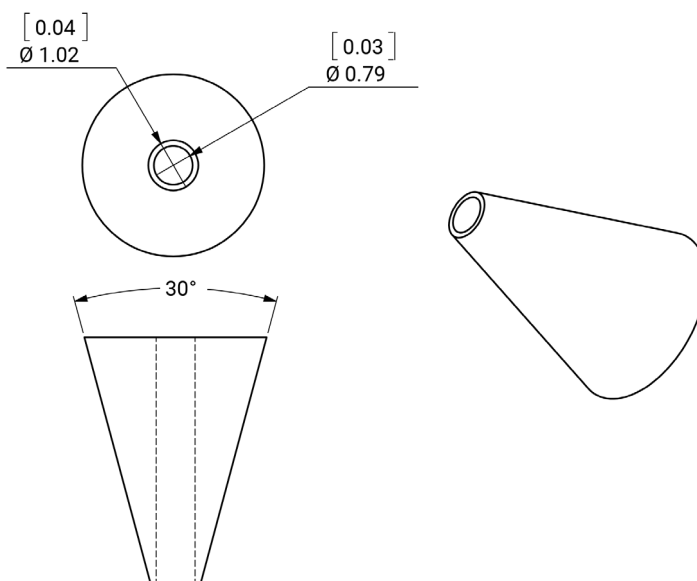
Whenever possible, Cree LED recommends the use of a pick & place tool to remove XLamp XE-G LEDs from the factory tape & reel packaging.

Pick & Place Nozzle

For pick and place nozzles coming into contact with silicone-covered LED components, Cree LED recommends nozzles be constructed of non-metallic materials. Cree LED and several of Cree LED's customers have had good success using nozzles fabricated from 95a urethane.

All dimensions in mm.

Measurement tolerances: .xxx = .001 mm



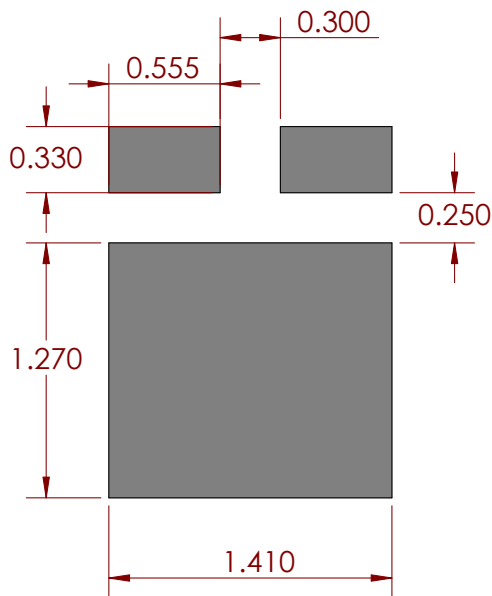
CIRCUIT BOARD PREPARATION & LAYOUTS

Printed circuit boards (PCBs) should be prepared and/or cleaned according to the manufacturer's specifications before placing or soldering XLamp XE-G LEDs onto the PCB.

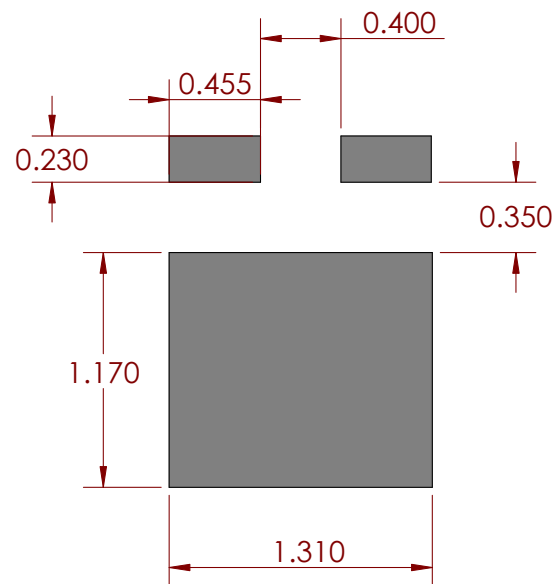
The diagram below shows the recommended PCB solder pad layout for XLamp XE-G LEDs.

All dimensions in mm.

Measurement tolerance: .xx = ± 13 mm



**Recommended Solder Pad
(Solder Mask Pattern)**



Recommended Stencil Openings

CASE TEMPERATURE (T_s) MEASUREMENT POINT

XLamp XE-G LED case temperature (T_s) should be measured on the PCB surface, as close to the LED's thermal pad as possible. Connect the thermocouple at a point where the voltage potential is below the rating for the meter. Cree LED recommends using a 36 AWG (0.01267 mm²) thermocouple wire for T_s measurements.

It is not required to use a solder footprint for the thermal pad that is larger than the XLamp XE-G LED itself. In testing, Cree LED has found such a solder pad to have insignificant impact on the resulting T_s measurement.

NOTES ON SOLDERING XLAMP® XE-G LEDs

XLamp XE-G LEDs are designed to be reflow soldered to a PCB. Reflow soldering may be done by a reflow oven or by placing the PCB on a hotplate and following the reflow soldering profile listed on page 7.

Do not wave solder XLamp XE-G LEDs. Do not hand solder XLamp XE-G LEDs.

✓
CORRECT



✓
CORRECT



✗
WRONG

Solder Paste Type

Cree LED strongly recommends using “no clean” solder paste with XLamp XE-G LEDs so that cleaning the PCB after reflow soldering is not required. Cree LED uses [Kester® R276 solder paste](#) internally.

Cree LED recommends the following solder paste compositions: SnAgCu (tin/silver/copper) and SnAg (tin/silver).

Solder Paste Thickness

The choice of solder and the application method will dictate the specific amount of solder. For the most consistent results, an automated dispensing system or a solder stencil printer is recommended. Cree LED has seen positive results using solder thickness that results in a 4-mil (102-μm) bond line, i.e., the solder joint thickness after reflow soldering.

✓
CORRECT



✗
WRONG

After Soldering

After soldering, allow XLamp XE-G LEDs to return to room temperature before subsequent handling. Handling of the device, especially around the lens, before cooling could result in damage to the LED.

Cree LED recommends verifying the solder process by checking the consistency of the solder bond of several trial PCBs after reflow. This can be done by X-ray or by shearing selected devices from the circuit board. The solder should appear completely re-flowed (no solder grains evident). The solder areas should show minimum evidence of voids on the backside of the package and the PCB.

Cleaning PCBs After Soldering

Cree LED recommends using “no clean” solder paste so that flux cleaning is not necessary after reflow soldering. If PCB cleaning is necessary, Cree LED recommends the use of isopropyl alcohol (IPA).

Do not use ultrasonic cleaning.

MOISTURE SENSITIVITY

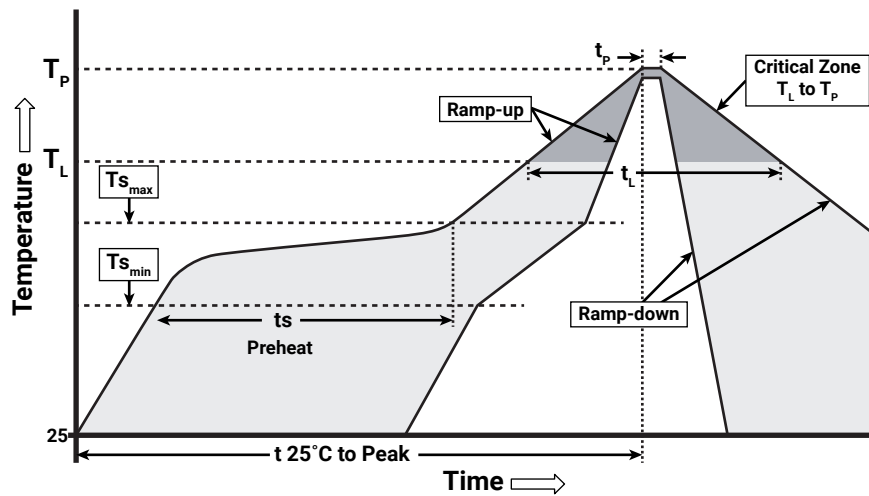
Cree LED recommends keeping XLamp LEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain XLamp LEDs do not need special storage for moisture sensitivity. Bare XLamp LEDs have a storage temperature range of -40 °C to 100 °C. However, the MBP, reel, tape and box have a more limited storage temperature range.

Once the MBP is opened, XLamp XE-G LEDs may be stored as MSL 1 per JEDEC J-STD-033, meaning they have unlimited floor life in conditions of ≤ 30 °C/85% relative humidity (RH). Regardless of storage condition, Cree LED recommends sealing any unsoldered LEDs in the original MBP.

XLAMP® XE-G LED REFLOW SOLDERING CHARACTERISTICS

In testing, Cree LED has found XLamp XE-G LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree LED recommends that users follow the recommended soldering profile provided by the manufacturer of the solder paste used, and therefore it is the lamp or luminaire manufacturer's responsibility to determine applicable soldering requirements.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



IPC/JEDEC J-STD-020C

Profile Feature	Lead-Free Solder
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	1.2 °C/second
Preheat: Temperature Min ($T_{s_{min}}$)	120 °C
Preheat: Temperature Max ($T_{s_{max}}$)	170 °C
Preheat: Time ($t_{s_{min}}$ to $t_{s_{max}}$)	65-150 seconds
Time Maintained Above: Temperature (T_L)	217 °C
Time Maintained Above: Time (t_L)	45-90 seconds
Peak/Classification Temperature (T_p)	235 - 245 °C
Time Within 5 °C of Actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	1 - 6 °C/second
Time 25 °C to Peak Temperature	4 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

CHEMICALS & CONFORMAL COATINGS

Below are representative lists of chemicals and materials to be used or avoided in LED manufacturing activities. For a complete and current list of recommended chemicals, conformal coatings and harmful chemicals consult Cree LED's [Chemical Compatibility Application Note](#).

Recommended Chemicals

In testing, Cree LED has found the following chemicals to be safe to use with XLamp XE-G LEDs.

- Water
- Isopropyl alcohol (IPA)

Chemicals Tested as Harmful

In general, subject to the specifics in Cree LED's [Chemical Compatibility Application Note](#), Cree LED has found certain chemicals to be harmful to XLamp XE-G LEDs. Cree LED recommends not using these chemicals anywhere in an LED system containing XLamp XE-G LEDs. The fumes from even small amounts of the chemicals may damage the LEDs.

- Chemicals that might outgas aromatic hydrocarbons (e.g., toluene, benzene, xylene)
- Methyl acetate or ethyl acetate (i.e., nail polish remover)
- Cyanoacrylates (i.e., "Superglue")
- Glycol ethers (including Radio Shack® Precision Electronics Cleaner - dipropylene glycol monomethyl ether)
- Formaldehyde or butadiene (including Ashland® PLIOBOND® adhesive)

Hermetically Sealing Luminaires

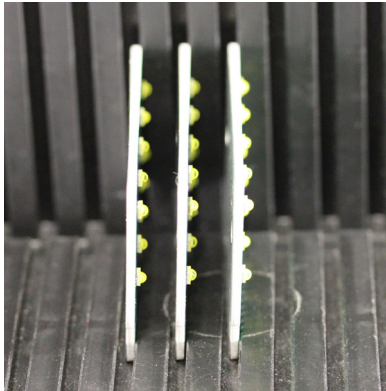
For proper LED operation and to avoid potential lumen depreciation and/or color shift, LEDs of all types must operate in an environment that contains oxygen. Simply allowing the LEDs to ventilate to air is sufficient; no extraordinary measures are required. Hermetically sealing LEDs in an enclosed space is not recommended.

ASSEMBLY STORAGE & HANDLING

Do not stack PCBs or assemblies containing XLamp XE-G LEDs so that anything rests on the LED lens. Force applied to the LED lens may result in the lens being knocked off. PCBs or assemblies containing XLamp XE-G LEDs should be stacked in a way to allow at least 1 cm clearance above the LED lens.

Do not use bubble wrap directly on top of XLamp XE-G LEDs. Force from the bubble wrap can potentially damage the LED.

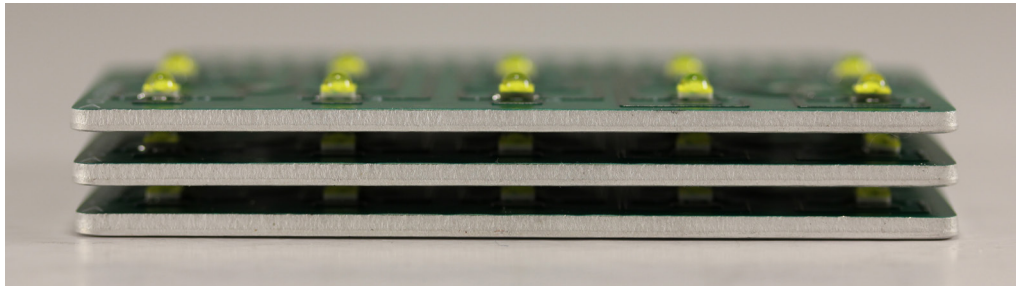
✓
CORRECT



✓
CORRECT



✗
WRONG

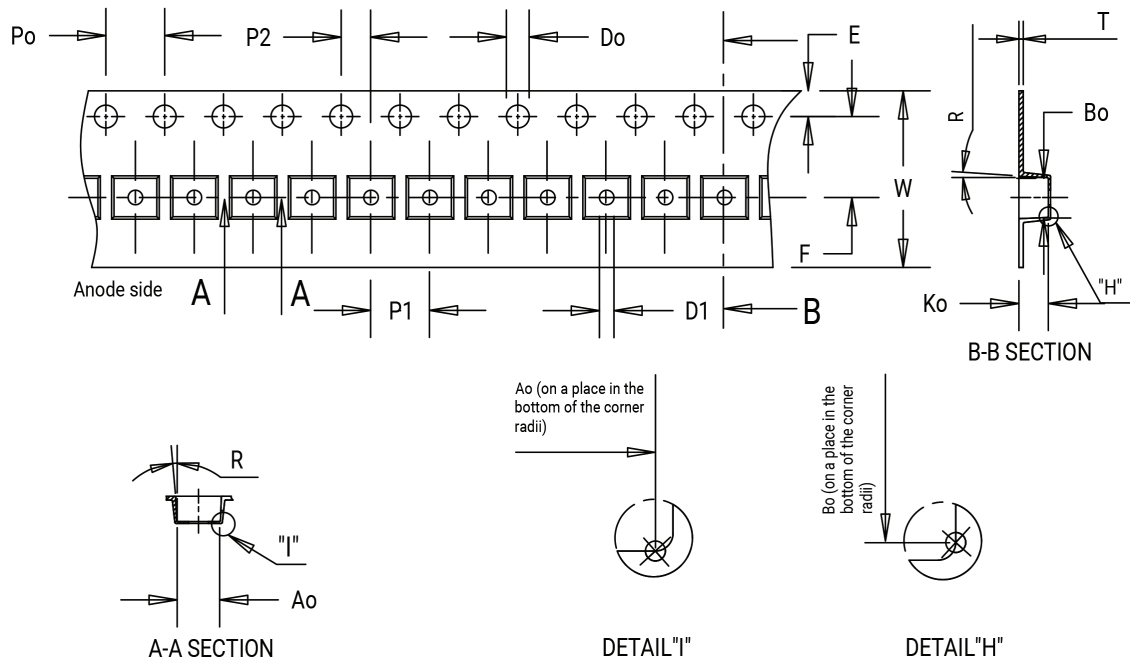


TAPE AND REEL

All Cree LED carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.

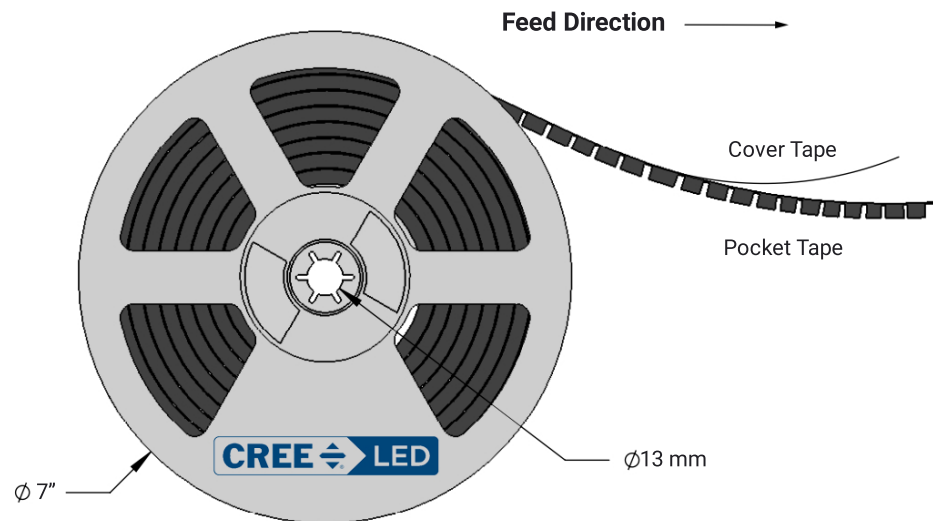
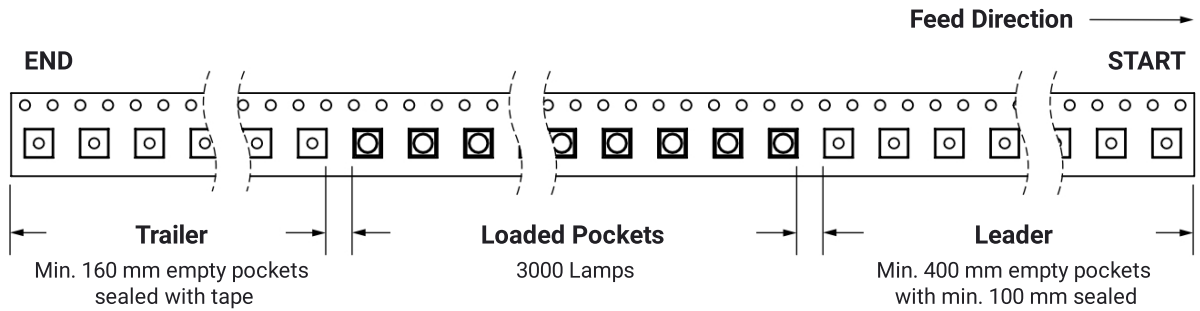
Except as noted, all dimensions in mm [in].

Measurement tolerances unless indicated otherwise: .xx = ±.15 mm



Item	Ao	Bo	Ko	Po	P1	P2	T	E	F	Do	D1	W	R
Dim.	1.85	2.30	1.30	4.00	4.00	2.00	0.30	1.75	3.50	1.50	1.00	8.00	3°

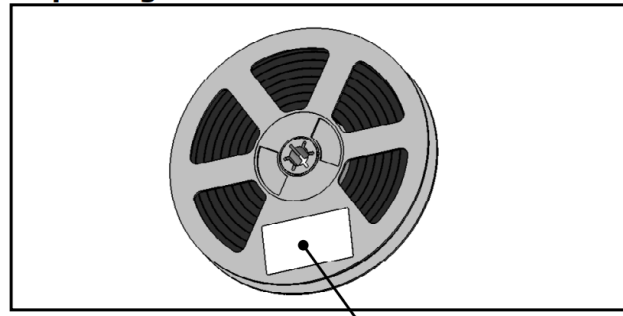
TAPE AND REEL - CONTINUED



PACKAGING & LABELS

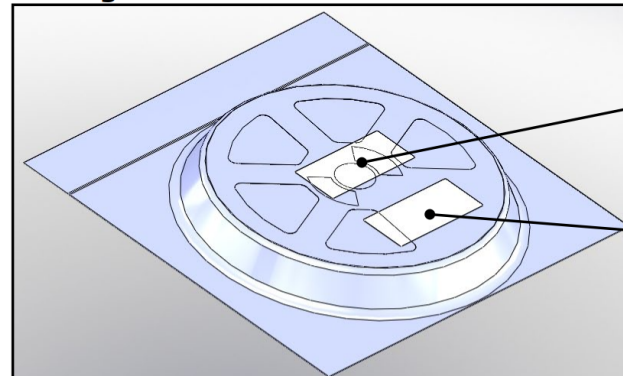
The diagrams below show the packaging and labels Cree LED uses to ship XLamp XE-G LEDs. XLamp XE-G LEDs are shipped in tape loaded on a reel. Each box contains only one reel in a moisture barrier bag.

Unpackaged Reel



Label with Cree LED Bin Code, Quantity, Reel ID

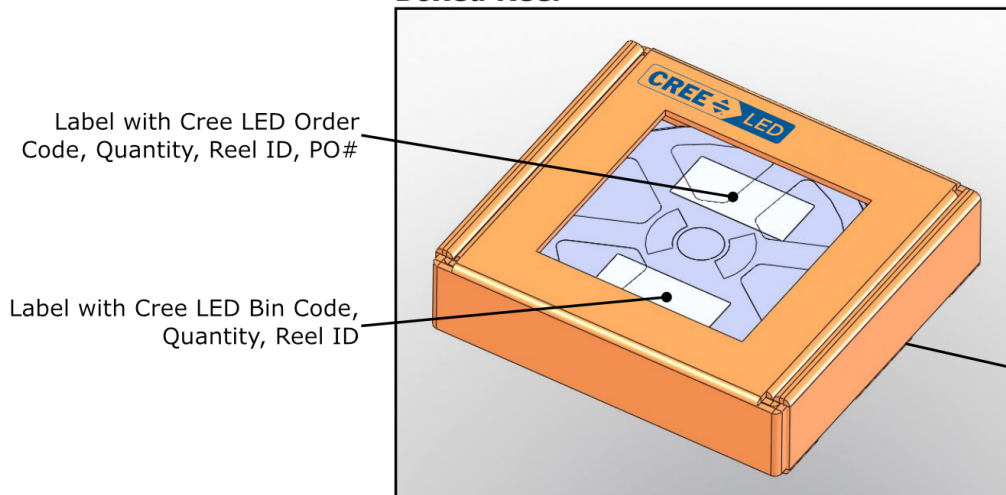
Packaged Reel



Label with Cree LED Order Code, Quantity, Reel ID, PO#

Label with Cree LED Bin Code, Quantity, Reel ID

Boxed Reel



Patent Label (on bottom of box)